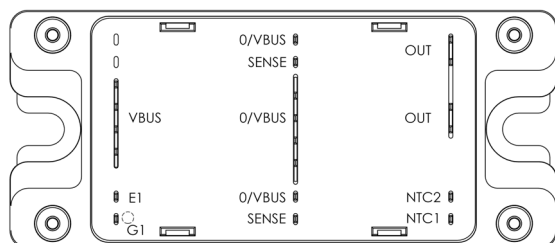
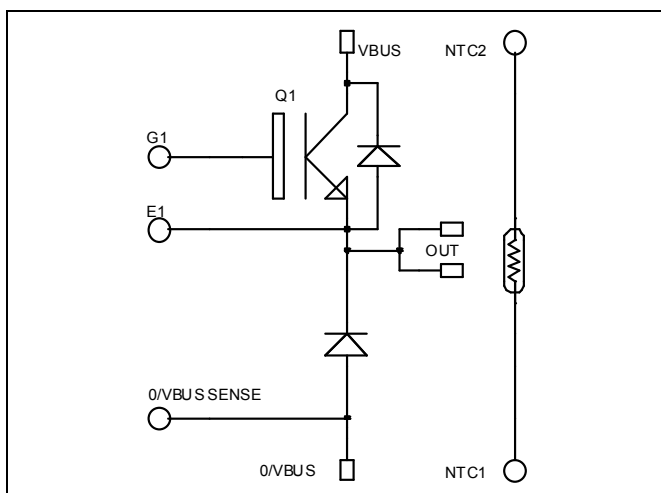


Buck chopper Trench + Field Stop IGBT3 Power Module

$V_{CES} = 1700V$
 $I_C = 100A @ T_c = 80^\circ C$



Application

- AC and DC motor control
- Switched Mode Power Supplies

Features

- Trench + Field Stop IGBT3 Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- High level of integration
- Internal thermistor for temperature monitoring

Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage	1700	V
I_C	Continuous Collector Current	$T_c = 25^\circ C$ 150 $T_c = 80^\circ C$ 100	A
I_{CM}	Pulsed Collector Current	$T_c = 25^\circ C$ 200	
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$ 560	W
RBSOA	Reverse Bias Safe Operating Area	$T_j = 125^\circ C$ 200A @ 1600V	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V, V_{CE} = 1700V$			250	μA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$V_{GE} = 15V$ $I_C = 100A$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	2.0 2.4	2.4	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 2mA$	5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20V, V_{CE} = 0V$			400	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0V$		9		nF
C_{oes}	Output Capacitance	$V_{CE} = 25V$		0.36		
C_{res}	Reverse Transfer Capacitance	$f = 1MHz$		0.3		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C)		370		ns
T_r	Rise Time	$V_{GE} = 15V$ $V_{Bus} = 900V$ $I_C = 100A$		40		
$T_{d(off)}$	Turn-off Delay Time	$R_G = 4.7 \Omega$		650		
T_f	Fall Time			180		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C)		400		ns
T_r	Rise Time	$V_{GE} = 15V$ $V_{Bus} = 900V$ $I_C = 100A$		50		
$T_{d(off)}$	Turn-off Delay Time	$R_G = 4.7 \Omega$		800		
T_f	Fall Time			300		
E_{on}	Turn-on Switching Energy	$V_{GE} = 15V$ $V_{Bus} = 900V$ $I_C = 100A$	$T_j = 125^\circ\text{C}$	32		mJ
E_{off}	Turn-off Switching Energy	$R_G = 4.7 \Omega$	$T_j = 125^\circ\text{C}$	31		

Chopper diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		1700			V
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1700V$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$		250 500	μA
I_F	DC Forward Current		$T_c = 80^\circ\text{C}$	100		A
V_F	Diode Forward Voltage	$I_F = 100A$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	1.8 1.9	2.2	V
t_{rr}	Reverse Recovery Time	$I_F = 100A$ $V_R = 900V$ $di/dt = 1000A/\mu s$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	385 490		ns
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	25 42		μC
E_r	Reverse Recovery Energy		$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	11 21		mJ



<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R ₂₅	Resistance @ 25°C		50		kΩ
B _{25/85}	T ₂₅ = 298.15 K		3952		K

$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

R_T : Thermistor value at T

<i>Symbol</i>	<i>Characteristic</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>	
R _{thJC}	Junction to Case Thermal Resistance		IGBT		0.22	°C/W	
			Diode		0.39		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz		4000			V	
T _J	Operating junction temperature range		-40		150	°C	
T _{STG}	Storage Temperature Range		-40		125		
T _C	Operating Case Temperature		-40		100		
Torque	Mounting torque	To Heatsink	M5	2.5		4.7	N.m
Wt	Package Weight					160	g

Technical drawing of a mechanical part, showing three views: Top View, Front View, and Side View. Dimensions are given in millimeters (mm) with tolerances.

Top View Dimensions:

- Overall Width: 93 ± 0.50
- Overall Height: 80 ± 0.20
- Left Side Features:
 - Top Hole Diameter: $\varnothing 6.1 \pm 0.2$
 - Top Hole Position: 17.20 ± 0.30 from top edge, 13 ± 0.50 from left edge.
 - Bottom Hole Diameter: $\varnothing 2 \pm 0.10$
 - Bottom Hole Position: 1 ± 0.10 from bottom edge, 7 ± 0.20 from left edge.
- Right Side Features:
 - Top Hole Diameter: $\varnothing 2.50 \pm 0.10$
 - Top Hole Position: 0.50 ± 0.05 from right edge.
 - Bottom Hole Diameter: $\varnothing 2 \pm 0.10$
 - Bottom Hole Position: 1 ± 0.10 from bottom edge, 7 ± 0.20 from right edge.

Front View Dimensions:

- Overall Width: 78.50 ± 0.25
- Overall Height: 17.20 ± 0.30
- Top Edge Features:
 - Top Hole Diameter: $\varnothing 6.1 \pm 0.2$
 - Top Hole Position: 17.20 ± 0.30 from top edge, 13 ± 0.50 from left edge.
 - Bottom Hole Diameter: $\varnothing 2 \pm 0.10$
 - Bottom Hole Position: 1 ± 0.10 from bottom edge, 7 ± 0.20 from left edge.
- Right Edge Features:
 - Top Hole Diameter: $\varnothing 2.50 \pm 0.10$
 - Top Hole Position: 0.50 ± 0.05 from right edge.
 - Bottom Hole Diameter: $\varnothing 2 \pm 0.10$
 - Bottom Hole Position: 1 ± 0.10 from bottom edge, 7 ± 0.20 from right edge.

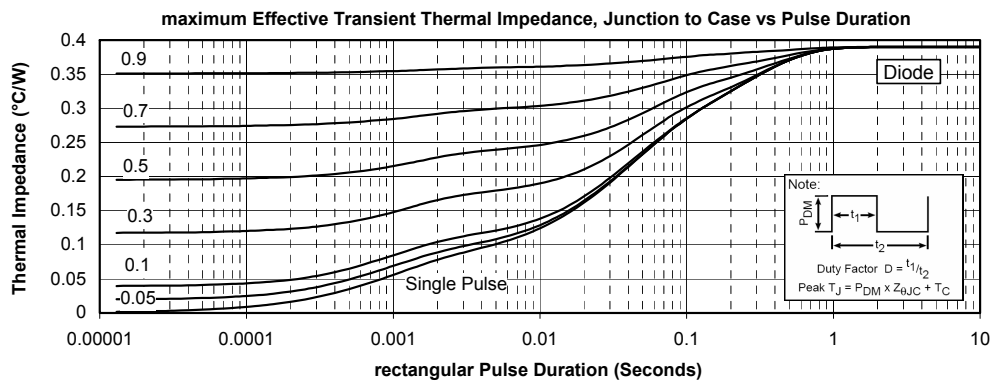
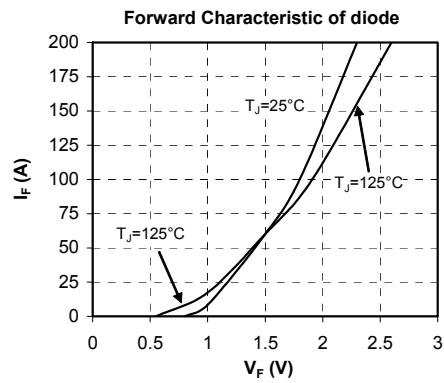
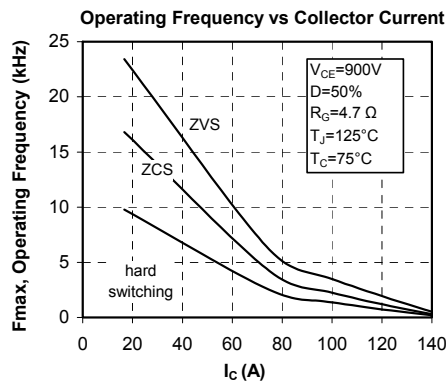
Side View Dimensions:

- Overall Width: 21.2 ± 1
- Overall Height: 40.40 ± 0.50
- Top Edge Features:
 - Top Hole Diameter: $\varnothing 6.1 \pm 0.2$
 - Top Hole Position: 17.20 ± 0.30 from top edge, 13 ± 0.50 from left edge.
 - Bottom Hole Diameter: $\varnothing 2 \pm 0.10$
 - Bottom Hole Position: 1 ± 0.10 from bottom edge, 7 ± 0.20 from left edge.
- Right Edge Features:
 - Top Hole Diameter: $\varnothing 2.50 \pm 0.10$
 - Top Hole Position: 0.50 ± 0.05 from right edge.
 - Bottom Hole Diameter: $\varnothing 2 \pm 0.10$
 - Bottom Hole Position: 1 ± 0.10 from bottom edge, 7 ± 0.20 from right edge.

ALL DIMENSIONS MARKED "±" ARE TOLERANCED AS : ± 0.1

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